

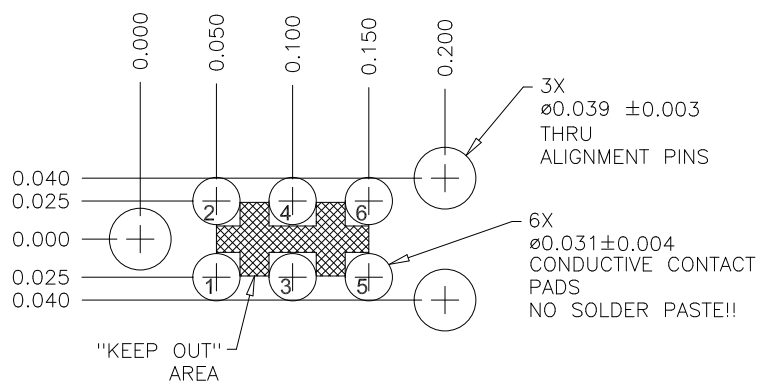
Notes

No tracks or vias in the shaded keepout area.

No other track or signal within 0.020" of any contact pad.

Do not allow solder paste on the contact pads. It is essential to eliminate any hole in the solder paste-mask (solder stencil) layer. If this is not possible make the contact pads thru-hole with finished hole size of 0.008" or less.

To avoid ordering confusion, please specify DNL in your BOM.

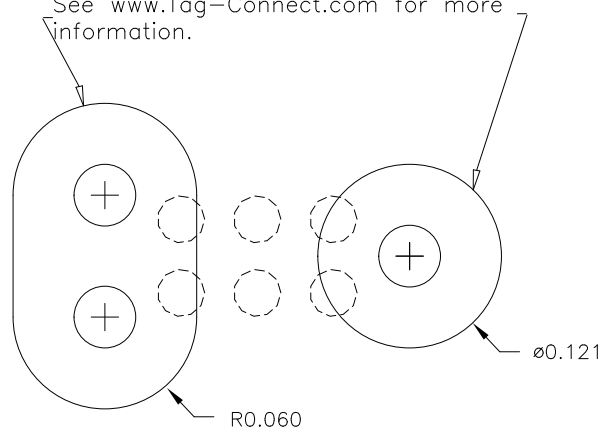


PCB TOP LAYER

Optional copper pads allow soldering of s/steel alignment pins to underside of board for debugging use. Use stainless steel soldering flux and care to avoid melting the connector.

Alternatives include the TC2030-CLIP board that grips the s/steel pins from the underside or Mill-Max receptacles P/N 0295-0-15-XX-06-XX-10-0

See www.Tag-Connect.com for more information.



OPTIONAL BOTTOM LAYER
ALTERNATIVE - USE TC2030-CLIP BOARD

Microchip ICD/ICSP Signals

Pin 1: -MCLR/Vpp

Pin 2: Vdd

Pin 3: Ground

Pin 4: PGD (ICSPDAT)

Pin 5: PGC (ICSPCLK)

Pin 6: Unused or LVP

www.TAG-CONNECT.com

TITLE
TC2030-MCP-NL-FP
FOOTPRINT FOR TC2030-MCP-NL

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UNLESS OTHERWISE NOTED
DIMENSIONS ARE IN INCHES

.XXX±	.XX±	ANGLE ±
.005	.01	1.5°

SCALE: 10:1

DRAWN
PM / NS
DATE
4/5/10

CHECKED
DATE

THIRD ANGLE PROJECTION

SIZE
A
SHEET 1 OF 1
DWG. NO.
REV.
D

CUSTOMER:

FILE: